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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
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OLIFF & BERRIDGE, PLC P.O. BOX 19928			PIZIALI, JEFFREY J		
ALEXANDRIA	, VA 22320		ART UNIT	PAPER NUMBER	
			2673		
			DATE MAILED: 12/01/2004	DATE MAILED: 12/01/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)		
		09/780,423	INUKAI, ATSUOMI		
Office Action Sum	mary	Examiner	Art Unit		
		Jeff Piziali	2673		
The MAILING DATE of this	s communication appe	ars on the cover sheet	with the correspondence address		
Period for Reply	NEDIOD 500 500 1				
A SHORTENED STATUTORY F THE MAILING DATE OF THIS C  - Extensions of time may be available under after SIX (6) MONTHS from the mailing date.  - If the period for reply specified above, the Failure to reply within the set or extended p Any reply received by the Office later than the earned patent term adjustment. See 37 CF	COMMUNICATION. the provisions of 37 CFR 1.136 e of this communication. s than thirty (30) days, a reply we e maximum statutory period will eriod for reply will, by statute, c hree months after the mailing d	(a). In no event, however, may vithin the statutory minimum of the apply and will expire SIX (6) M6 ause the application to become	a reply be timely filed  nirty (30) days will be considered timely.  DNTHS from the mailing date of this communication.  ABANDONED (35 U.S.C. § 133).		
Status					
1) Responsive to communica	ition(s) filed on 16 Jun	e 2004.			
2a)⊠ This action is <b>FINAL</b> .					
3) Since this application is in closed in accordance with			atters, prosecution as to the merits is .D. 11, 453 O.G. 213.		
Disposition of Claims					
4)	is/are withdrawr wed. s/are rejected. cted to.	from consideration.			
Application Papers					
9) The specification is objecte	d to by the Examiner.				
10)⊠ The drawing(s) filed on <u>12</u>	February 2001 is/are:	a)⊠ accepted or b)□	] objected to by the Examiner.		
Applicant may not request that	at any objection to the dr	awing(s) be held in abey	ance. See 37 CFR 1.85(a).		
			g(s) is objected to. See 37 CFR 1.121(d). ed Office Action or form PTO-152.		
Priority under 35 U.S.C. § 119					
<ul><li>2. Certified copies of the</li><li>3. Copies of the certified</li></ul>	None of: ne priority documents in ne priority documents in	have been received. have been received in y documents have bee	§ 119(a)-(d) or (f).  Application No  In received in this National Stage		
* See the attached detailed O	ffice action for a list of	the certified copies no	ot received.		
Attachment(s)					
1) Notice of References Cited (PTO-892)	•	4) Interview	Summary (PTO-413)		
<ol> <li>Notice of Draftsperson's Patent Drawin</li> <li>Information Disclosure Statement(s) (P Paper No(s)/Mail Date</li> </ol>		Paper No	o(s)/Mail Date f Informal Patent Application (PTO-152)		

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#### **DETAILED ACTION**

#### **Priority**

1. Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

# Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 3. Claims 1-4, 7-10, and 12-15 are rejected under 35 U.S.C. 102(e) as being anticipated by Maeda (US 6,512,510).

Regarding claim 1, Maeda discloses a pointing device [Figs. 1 & 3; P1] including: a sensor substrate [Figs. 2 & 3; 8] having a flat board form; a stick member [Fig. 3; 2] vertically provided on an upper surface of the sensor substrate; at least a pair of strain sensors [Fig. 3; 9a & 9c] arranged in symmetrical relation to each other with respect to the stick member; and a slit [Fig. 3; 6 & 8d] formed on the sensor substrate near the strain sensor, the slit remaining on the sensor substrate and having parallel slit portions which are provided at both sides of each of the strain sensors to form an intersecting area [Fig. 3; 4a-4d] of the sensor substrate between the parallel slit portions, wherein the slit induces an increase in an amount of deformation generated

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in the intersecting area of the sensor substrate during operation of the stick member, wherein the sensor substrate includes: a strain detecting substrate section [Fig. 3; 4a-4d] on which the stick member and the strain sensors are disposed, this section being used for detecting an amount of strain of the sensor substrate by means of the strain sensors, the strain being caused by operation of the stick member; a signal processing substrate section [Figs. 2 & 3; 10] for signal processing [i.e. signal transferring] the strain amount of the sensor substrate detected by the strain detecting substrate section; a connecting substrate section [Figs. 2 & 3; 8c] which is narrower in width than the strain detecting substrate section and the signal processing substrate section, the connecting substrate section connecting the strain detecting substrate section and the signal processing substrate section, wherein the strain detecting substrate section, the signal processing substrate section and the connecting substrate section are integrally formed in the sensor substrate (see Column 5, Line 34 - Column 6, Line 64).

Regarding claim 2, Maeda discloses the sensor substrate is made of a flexible insulative material (see Column 5, Lines 61-65).

Regarding claim 3, Maeda discloses the strain sensor is made of a resistive material which changes its resistance value with stress applied to the strain sensor (see Column 5, Line 66 - Column 6, Line 64).

Regarding claim 4, Maeda discloses the resistance material is formed adhering onto the insulative material by a layer forming technique (see Column 5, Line 66 - Column 6, Line 31).

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Regarding claim 7, Maeda discloses another pair of strain sensors [Fig. 3; 9b & 9d] arranged on the sensor substrate in a direction [Fig. 3; Y1] perpendicular to a line [Fig. 3; X1] connecting the first pair of strain sensors while passing through a center of the stick member, wherein the strain sensors are arranged at 90 degree angular intervals around the stick member (see Column 6, Lines 1-64).

Regarding claim 8, Maeda discloses the slit portions formed between the strain sensors adjacently arranged are connected to form the slit in an L-shape (see Fig. 3; Column 5, Lines 39-65).

Regarding claim 9, Maeda discloses four L-shaped slits are formed at 90 degree angular intervals around the stick member, and the four L-shaped slits jointly form a cross-shaped intersecting area (see Fig. 3; Column 5, Line 39 - Column 6, Line 3).

Regarding claim 10, Maeda discloses chip resistances [Fig. 3; 10] capable of being trimmed, connected in series with the strain sensors correspondingly and arranged out of the intersecting area on the sensor substrate (see Column 6, Lines 1-31).

Regarding claim 12, Maeda discloses the connecting substrate section is produced by formation of cut-out portions from both sides of the sensor substrate in its width direction toward a center thereof (see Figs. 2 & 3; Column 5, Line 54 - Column 6, Line 64).

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Regarding claim 13, Maeda discloses an engagement member portion [Fig. 3; 3] protruding from a lower end of the stick member; an attachment hole [Fig. 3; 8a] formed in the sensor substrate, in which the engagement portion is inserted; and a fixing member [Fig. 3; 12] for fixing the engagement portion of the stick member inserted in the attachment hole, the fixing member being attached from a back surface of the sensor substrate; wherein the stick member is vertically provided on the sensor substrate in an engagement relation thereto (see Fig. 3; Column 6, Lines 13-31).

Regarding claim 14, this claim is rejected by the reasoning applied in the above rejection of claim 1, furthermore Maeda discloses a keyboard [Fig. 1] provided with a plurality of keys [Fig. 1; 27] arranged on a keyboard substrate and a pointing device [Fig. 1; P1] mounted on a part of an operating face of the keyboard (see Column 1, Line 15 - Column 2, Line 41).

Regarding claim 15, this claim is rejected by the reasoning applied in the above rejection of claims 1 and 14, furthermore Maeda discloses a controller [i.e. computer] for controlling various data [i.e. signals] input with the keys on the keyboard; and a display [i.e. inherent for cursor display] for displaying the data [i.e. cursor signals] under control by the controller (see Column 1, Line 41 - Column 2, Line 28).

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## Claim Rejections - 35 USC § 103

- 4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. Claims 5 and 6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Maeda et al. (US 6,512,510).

Regarding claim 5, Maeda does not expressly disclose the layer forming technique is selected from among a vacuum deposition method, a sputter method, and a vapor phase deposition method. However, such layer forming techniques were well known and commonly understood at the time of invention. Therefore, it would have been obvious to one skilled in the art at the time of invention to use a vacuum deposition method, a sputter method, or a vapor phase deposition method as Maeda's layer forming technique, so as to form the resistance material adhering to the insulative material using traditionally appropriate and operationally successful layering methods.

Regarding claim 6, Maeda does not expressly disclose the resistance material is mainly composed of carbon. However, resistance materials made mainly of carbon were well known and commonly understood at the time of invention. Therefore, it would have been obvious to one skilled in the art at the time of invention to use mainly carbon as Maeda's resistance material, so as to compose the resistance material using a operationally appropriate and commonly available material.

6. Claims 16-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Maeda et al. (US 6,512,510) in view of the present application's own admission of prior art.

Regarding claim 16, Maeda does not expressly disclose each of the strain sensors is formed with a plurality of windows in which the resistance material is absent, the windows being arranged in aligned relation to a line connecting the pair of strain sensors while passing through a center of the stick member, and also each of the strain sensors is formed with a notch which is made by a trimming process of irradiating a laser beam to the strain sensor along the alignment direction of the windows.

However, the present application discloses, as prior art, forming strain sensors [Fig. 14; 153] with a plurality of windows in which the resistance material is absent, the windows being arranged in aligned relation to a line connecting the pair of strain sensors while passing through a center of the stick member, and also each of the strain sensors is formed with a notch [Fig. 14, 153a] which is made by a trimming process of irradiating a laser beam to the strain sensor along the alignment direction of the windows (see Figs. 14 & 15; Page 2, Line 21 - Page 3, Line 27). Maeda and the present application's prior art disclosure are analogous art, because they are from the shared field of strain sensing pointing devices. Therefore, it would have been obvious to one skilled in the art at the time of invention to use such a strain sensor formation as Maeda's strain sensor circuitry, so as to prevent the inconsistency in an offset voltage outputted due to the sensors.

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Regarding claim 17, the present application discloses, as prior art, the trimming process making the notch so that an endpoint of the notch is received within the window (see Figs. 14 & 15; Page 2, Line 21 - Page 3, Line 27).

Regarding claim 18, Maeda does not expressly disclose that the resistance material is formed adhering onto the insulative material by a thick layer printing technique. However, such a layer forming method was well known and commonly understood at the time of invention. Therefore, it would have been obvious to one skilled in the art at the time of invention to use a thick layer printing technique as Maeda's layer forming method, so as to form the resistance material adhering to the insulative material using a traditionally appropriate and operationally successful layering method.

Regarding claim 19, Maeda does not expressly disclose that the resistance material is a ruthenium material. However, resistance materials made from ruthenium materials were well known and commonly understood at the time of invention. Therefore, it would have been obvious to one skilled in the art at the time of invention to use ruthenium material as Maeda's resistance material, so as to compose the resistance material using a operationally appropriate and commonly available material.

Regarding claim 20, Maeda does not expressly disclose the ruthenium material is ruthenium dioxide. However, resistance materials made ruthenium dioxide were well known and commonly understood at the time of invention. Therefore, it would have been obvious to one

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skilled in the art at the time of invention to use ruthenium dioxide as Maeda's resistance material, so as to compose the resistance material using a operationally appropriate and commonly available material.

## Response to Arguments

7. Applicant's arguments filed 16 June 2004 have been fully considered but they are not persuasive. The applicant contends the cited prior art of Maeda (US 6,512,510) neglects teaching a strain detecting substrate section, signal processing substrate section, and connecting substrate section integrally formed in a sensor substrate. However, the examiner respectfully disagrees. Maeda explicitly discloses a strain detecting substrate section [Fig. 3; 4a-4d] on which a stick member [Fig. 3; 2] and plural strain sensors [Fig. 3; 9a-9d] are disposed, this section being used for detecting an amount of strain of a sensor substrate [Figs. 2 & 3; 8] by means of the strain sensors, the strain being caused by operation of the stick member; a signal processing substrate section [Figs. 2 & 3; 10] for signal processing [i.e. signal transferring] the strain amount of the sensor substrate detected by the strain detecting substrate section; a connecting substrate section [Figs. 2 & 3; 8c] which is narrower in width than the strain detecting substrate section and the signal processing substrate section, the connecting substrate section connecting the strain detecting substrate section and the signal processing substrate section, wherein the strain detecting substrate section, the signal processing substrate section and the connecting substrate section are integrally formed in the sensor substrate (see Column 5, Line 34 - Column 6, Line 64). By such reasoning, rejection of the claims is deemed necessary, proper, and thereby maintained at this time.

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#### Conclusion

8. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jeff Piziali whose telephone number is (703) 305-8382. The examiner can normally be reached on Monday - Friday (6:30AM - 3PM).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bipin Shalwala can be reached on (703) 305-4938. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

29 November 2004

BIPIN SHALWALA

SUPERVISORY PATENT EXAMINER
TECHNOLOGY CENTER 2600